

BS EN 62047-22:2014



BSI Standards Publication

Semiconductor devices — Micro-electromechanical devices

Part 22: Electromechanical tensile test
method for conductive thin films on
flexible substrates

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The UK participation in its preparation was entrusted to Technical Committee EPL/47, Semiconductors.

A list of organizations represented on this committee can be obtained on request to its secretary.

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Amendments/corrigenda issued since publication

Date	Text affected
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English Version

**Semiconductor devices - Micro-electromechanical devices -
Part 22: Electromechanical tensile test method for conductive
thin films on flexible substrates
(IEC 62047-22:2014)**

Dispositifs à semiconducteurs - Dispositifs
microélectromécaniques -
Partie 22: Méthode d'essai de traction électromécanique
pour les couches minces conductrices sur des substrats
souples
(CEI 62047-22:2014)

Halbleiterbauelemente - Bauelemente der
Mikrosystemtechnik -
Teil 22: Elektromechanisches Zug-Prüfverfahren für
leitfähige Dünnschichten auf flexiblen Substraten
(IEC 62047-22:2014)

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European Committee for Electrotechnical Standardization
Comité Européen de Normalisation Electrotechnique
Europäisches Komitee für Elektrotechnische Normung

CEN-CENELEC Management Centre: Avenue Marnix 17, B-1000 Brussels

Foreword

The text of document 47F/186/FDIS, future edition 1 of IEC 62047-22, prepared by SC 47F "Microelectromechanical systems" of IEC/TC 47 "Semiconductor devices" was submitted to the IEC-CENELEC parallel vote and approved by CENELEC as EN 62047-22:2014.

The following dates are fixed:

- latest date by which the document has to be (dop) 2015-04-24
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publication of an identical national
standard or by endorsement
- latest date by which the national (dow) 2017-07-24
standards conflicting with the
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Annex ZA (normative)

Normative references to international publications with their corresponding European publications

The following documents, in whole or in part, are normatively referenced in this document and are indispensable for its application. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

NOTE 1 When an International Publication has been modified by common modifications, indicated by (mod), the relevant EN/HD applies.

NOTE 2 Up-to-date information on the latest versions of the European Standards listed in this annex is available here: www.cenelec.eu

<u>Publication</u>	<u>Year</u>	<u>Title</u>	<u>EN/HD</u>	<u>Year</u>
IEC 62047-2	2006	Semiconductor devices - Micro-electromechanical devices - Part 2: Tensile testing method of thin film materials	EN 62047-2	2006
IEC 62047-3	2006	Semiconductor devices - Micro-electromechanical devices - Part 3: Thin film standard test piece for tensile testing	EN 62047-3	2006
IEC 62047-8	2011	Semiconductor devices - Micro-electromechanical devices - Part 8: Strip bending test method for tensile property measurement of thin films	EN 62047-8	2011
ISO 527-3	1995	Plastics - Determination of tensile properties - Part-3: Test conditions for films and sheets	EN ISO 527-3	1995